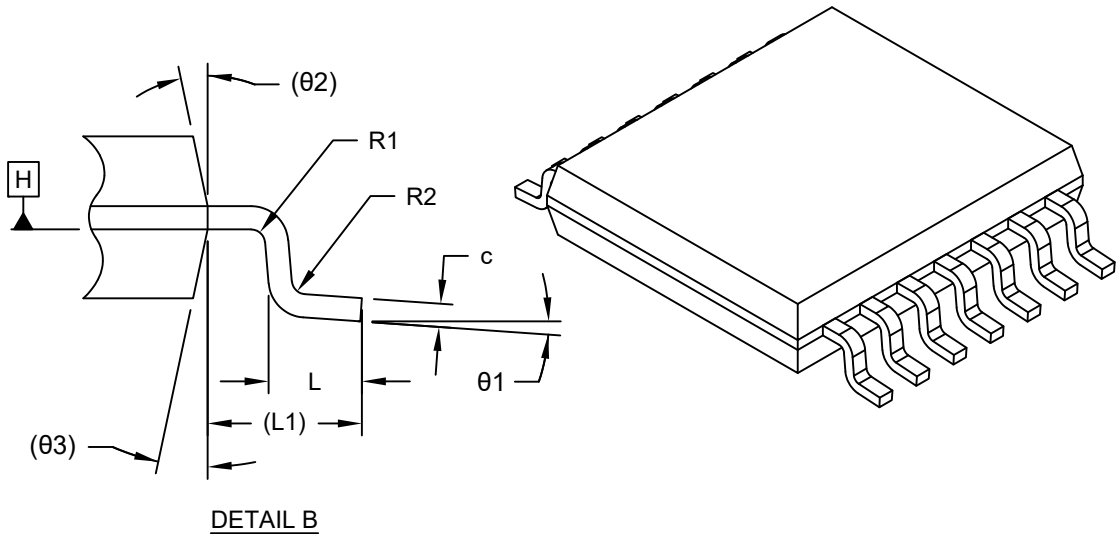


14-Lead Thin Shrink Small Outline Package [ST] – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		14		
Pitch	e		0.65 BSC		
Overall Height	A	–	–		1.20
Standoff	A1	0.05	–		0.15
Molded Package Thickness	A2	0.80	1.00		1.05
Overall Length	D	4.90	5.00		5.10
Overall Width	E		6.40 BSC		
Molded Package Width	E1	4.30	4.40		4.50
Terminal Width	b	0.19	–		0.30
Terminal Thickness	c	0.09	–		0.20
Terminal Length	L	0.45	0.60		0.75
Footprint	L1		1.00 REF		
Lead Bend Radius	R1	0.09	–		–
Lead Bend Radius	R2	0.09	–		–
Foot Angle	θ1	0°	–		8°
Mold Draft Angle	θ2	–	12° REF		–
Mold Draft Angle	θ3	–	12° REF		–

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.